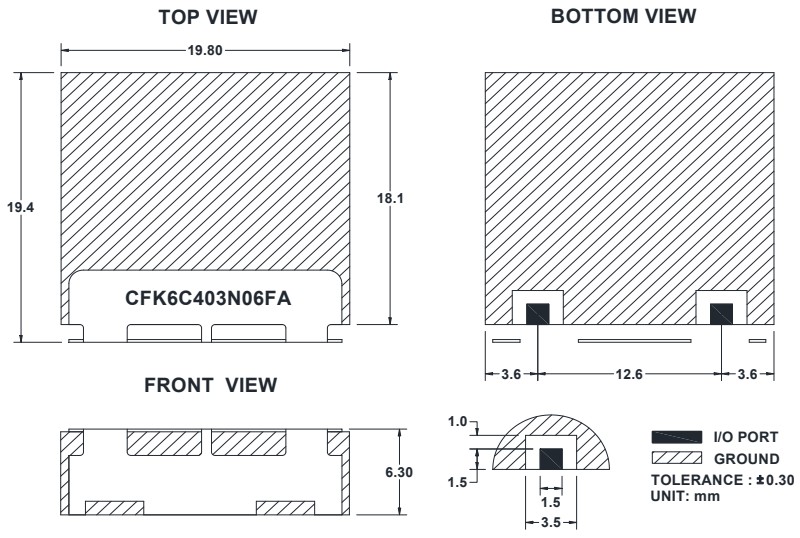
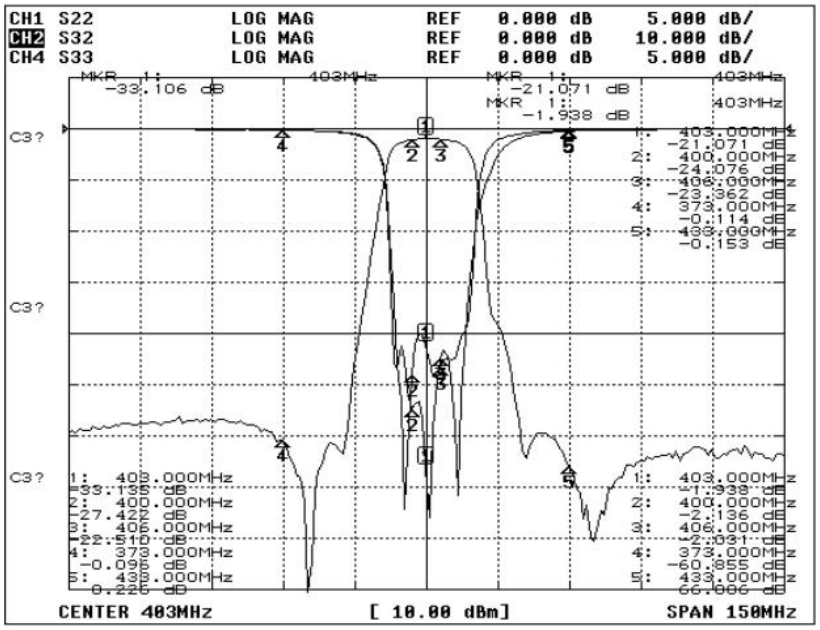
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	403.0	MHz
BD Bandwidth [BW]	fo ±3.0 [400.0 ~ 406.0]	MHz
Insertion Loss in BW	3.0	dB max
Ripple in BW	0.5	dB max
Return Loss in BW	15.0	dB min
Attenuation ☑ Absolute Value ☐ Relative Value	40.0 dB min @ fo ± 30.0 [373.0 & 433.0]	MHz
	dB min @ fo ± [&]	MHz
	dB min @ fo ± [&]	MHz
	dB min @ fo ± [&]	MHz
Group Delay Variation		ns max
Input Power	3.0	W max
In/Out Impedance	50 Ω	
Operation Temperature Range	-40℃ to +85℃	

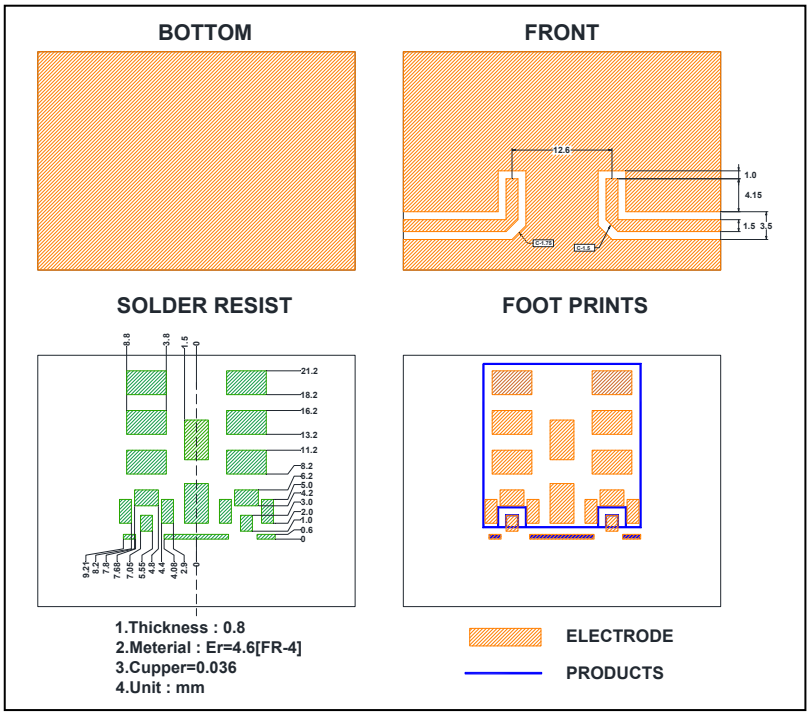
Mechanical Specification



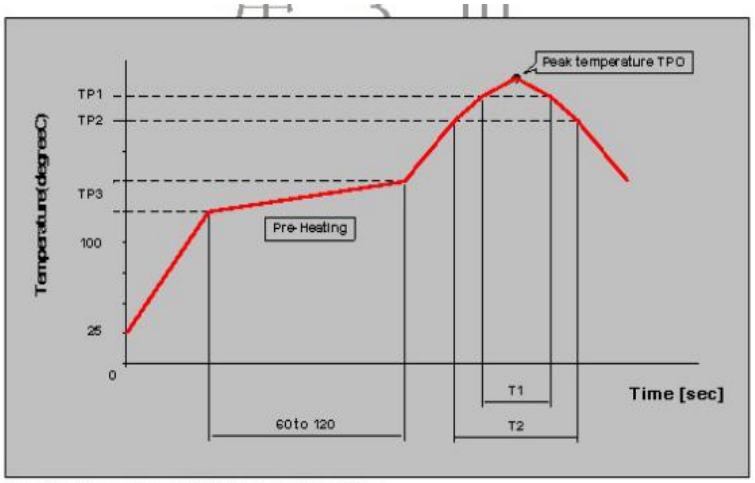
Plot Data



Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180